



FACTSHEET

**MAXA 2010
Finalist**

Company	STATS ChipPAC Ltd.
Boiler-Plate	STATS ChipPAC Ltd. is a leading service provider of semiconductor packaging design, assembly, test and distribution solutions in diverse end market applications including communications, digital consumer and computing. With global headquarters in Singapore, STATS ChipPAC has design, research and development, manufacturing or customer support offices in 10 different countries. STATS ChipPAC is listed on the SGX-ST. Further information is available at www.statschippac.com .
Recent Announcements	<ul style="list-style-type: none"> • STATS ChipPAC Drives Innovation in Low Cost Flip Chip Technology with Copper Column Bump (26 May 10) • STATS ChipPAC Honored 5 Companies with 2009 Supplier Excellence Awards (18 May 10) • STATS ChipPAC Honored by Samsung with Best Supplier Award (10 May 10) • STATS ChipPAC Received AMD's World Class Supplier Achievement Award (6 May 10) • STATS ChipPAC First to Implement 300mm Manufacturing for eWLB Technology (18 Apr 10) • STATS ChipPAC Receives Analog Devices' Supplier Excellence Award for the Second Consecutive Year (23 Mar 10)

Award Partners: Singapore Economic Development Board . McKinsey & Company . Singapore Manufacturing Federation . Singapore-MIT Alliance

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<p>Leadership Position (Global/Asia)</p>	<ul style="list-style-type: none"> • STATS ChipPAC is the 4th largest Outsourced Assembly and Test (OSAT) provider worldwide • STATS ChipPAC Singapore has established a clear leadership position in wafer level manufacturing such as embedded Wafer Level Ball Grid Array (eWLB) technology <ul style="list-style-type: none"> ○ First in the world to achieve high volume eWLB manufacturing levels with best-in-class yields ○ First in the world to implement 300mm eWLB wafer manufacturing • Broad portfolio of leaded, laminate and wafer level packaging technology • Rapidly ramping new copper wirebond capabilities for customers • One of the world’s largest mixed signal and RF test providers
<p>Efforts to Achieve Manufacturing Excellence</p>	<ul style="list-style-type: none"> • STATS ChipPAC Singapore utilizes Lean Six Sigma methodology to drive breakthroughs in manufacturing performance • Robust quality system that has consistently been recognized by Intel with its prestigious Supplier Continuous Quality Improvement Award • Numerous customer recognition awards from companies such as AMD, Analog Devices, LSI, Samsung, etc. • Driving manufacturing innovation in wafer level technology, eWLB, integrated passive devices and copper wire bond packaging • Developed innovative IT program to drive automation in the test process to achieve higher levels of quality, increased throughput and increased efficiency • Established numerous employee programs to train, recognize and reward employees for individual contributions to manufacturing excellence and innovation